High Voltage Power Transistors

DPAK for Surface Mount Applications

Designed for line operated audio output amplifier, switchmode power supply drivers and other switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular MJE340 and MJE350
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	300	Vdc
Collector-Base Voltage	V _{CB}	300	Vdc
Emitter-Base Voltage	V _{EB}	3	Vdc
Collector Current – Continuous	I _C	0.5	Adc
Collector Current - Peak	I _{CM}	0.75	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	15 0.12	W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.56 0.012	W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C
ESD – Human Body Model	HBM	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

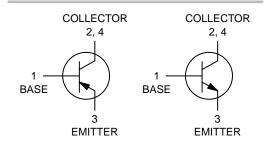
 These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

http://onsemi.com

SILICON POWER TRANSISTORS 0.5 AMPERE 300 VOLTS, 15 WATTS





DPAK CASE 369C STYLE 1

MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week
J3x0 = Device Code

= Device Code x= 4 or 5

G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	8.33	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	80	°C/W
Leading Temperature for Soldering Purpose	TL	260	°C

^{2.} These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS	OFF CHARACTERISTICS				
Collector–Emitter Sustaining Voltage (Note 3) $(I_C = 1 \text{ mA}, I_B = 0)$	V _{CEO(sus)}	300	-	V	
Collector Cutoff Current (V _{CB} = 300 V, I _E = 0)	I _{CEO}	-	0.1	mA	
Emitter Cutoff Current (V _{BE} = 3 V, I _C = 0)	I _{EBO}	-	0.1	mA	
ON CHARACTERISTICS (Note 3)		•		•	
DC Current Gain (I _C = 50 mA, V _{CE} = 10 V)	h _{FE}	30	240	_	
Collector–Emitter Saturation Voltage (I _C = 100 mA, I _B = 10 mA)	V _{CE(sat)}	-	1	V	
Base–Emitter On Voltage (I _C = 1 A, V _{CE} = 10 V)	V _{BE(on)}	-	1.5	V	
DYNAMIC CHARACTERISTICS	-	•		•	
Current Gain – Bandwidth Product (I _C = 50 mA, V _{CE} = 10 V, f = 10 MHz)	f _T	10	-	MHz	

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

TYPICAL CHARACTERISTICS

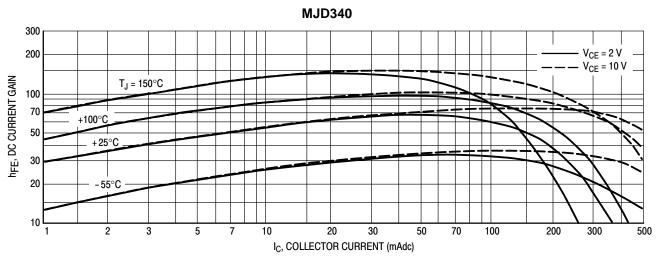


Figure 1. DC Current Gain

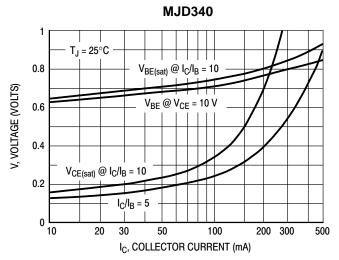
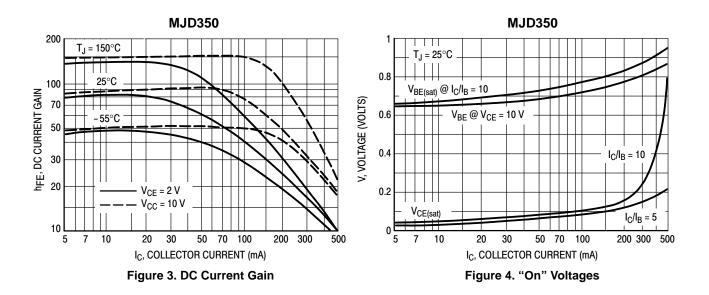


Figure 2. "On" Voltages



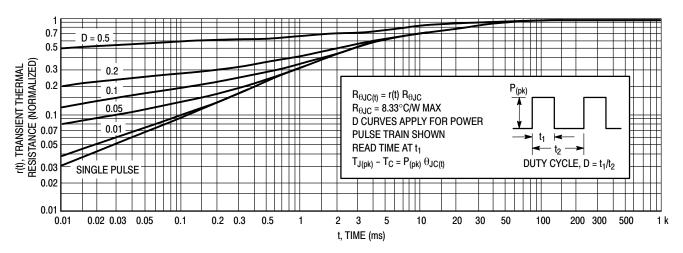


Figure 5. Thermal Response

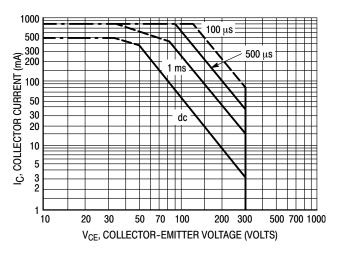


Figure 6. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_{J(pk)} = 150^{\circ} C$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ} C$. $T_{J(pk)}$ may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

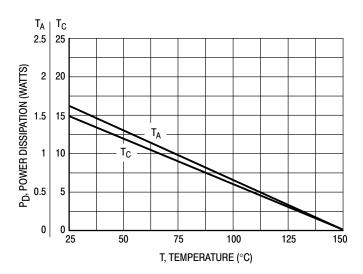


Figure 7. Power Derating

ORDERING INFORMATION

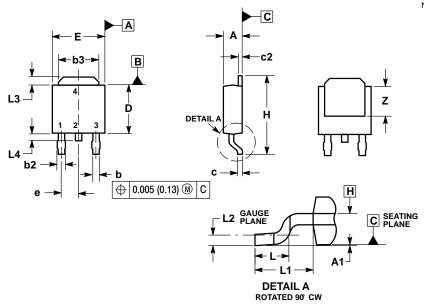
Device	Package	Shipping [†]
MJD340G	DPAK (Pb-Free)	75 Units / Rail
MJD340RLG	DPAK (Pb-Free)	1,800 / Tape & Reel
MJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
MJD350G	DPAK (Pb-Free)	75 Units / Rail
MJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE D



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- CONTROLLING DIMENSION: INCHES.
 THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD 4. DIMENSIONS D AND E DO NOT INCLUDE MOCLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM

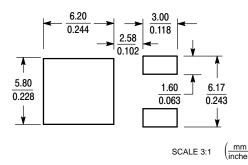
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

STYLE 1:

- PIN 1. BASE 2. COLLECTOR

 - EMITTER COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Website:

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Contact Us:

> Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com